

NOT RECOMMENDED FOR NEW DESIGN **USE DMP21D6UFD**



DMP21D5UFD

P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} MAX	Package	I _D T _A = +25°C
-20V	1.0Ω @ V _{GS} = -4.5V		-600mA
	1.5Ω @ $V_{GS} = -2.5V$	V4 DEN4040.0	-500mA
	2.0Ω @ V _{GS} = -1.8V	X1-DFN1212-3	-400mA
	3.0Ω @ V _{GS} = -1.5V		-250mA

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- **DC-DC Converters**
- Power Management Functions

Features

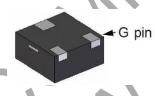
- Low On-Resistance
- Very Low Gate Threshold Voltage $V_{GS(TH)}$, 1.0V Max
- Low Input Capacitance
- Fast Switching Speed
- **ESD Protected Gate**
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

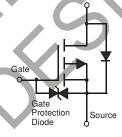
Mechanical Data

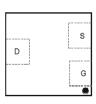
- Case: X1-DFN1212-3
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 @4)
- Terminal Connections: See Diagram
- Weight: 0.005 grams (Approximate)











Bottom View Top View

Equivalent Circuit

Pin-Out Top View

Ordering Information (Note 4)

Part Number	Case	Packaging
DMP21D5UFD-7	X1-DFN1212-3	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.</p>
 For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

KP2 YM

KP2 = Product Type Marking Code YM = Date Code Marking Y = Year (ex: E = 2017)M = Month (ex: 9 = September)

Date Code Kev

		_									_	
Year	201	1	2012		2013	20	14	2015		2016	2	2017
Code	Υ		Z		Α	[3	С		D		Е
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



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DMP21D5UFD

Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	V_{DSS}	-20	V	
Gate-Source Voltage		V_{GSS}	±8	V
Continuous Drain Current (Note 6) V _{GS} = -4.5V	ID	-600 -500	mA	
Continuous Drain Current (Note 6) V _{GS} = -1.8V	Ι _D	-400 -300	mA	
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	-2	Α	
Maximum Body Diode Continuous Current		I _S	-800	mA

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)		PD	0.4	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ heta JA}$	280	°C/W
Total Power Dissipation (Note 6)		PD	0.8	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{ heta JA}$	140	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +150	°C

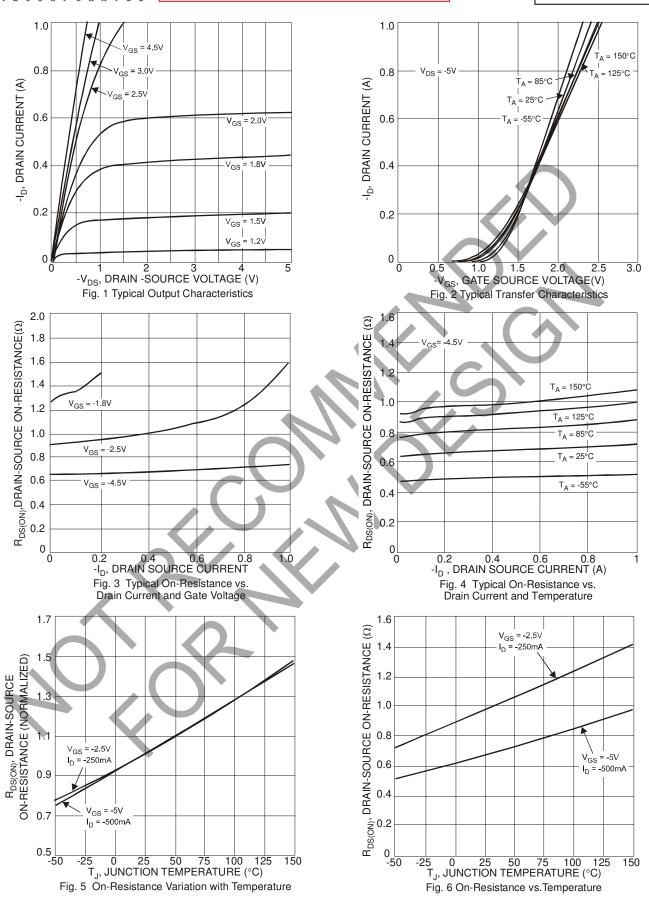
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	\	V	$V_{GS} = 0V$, $I_D = -1mA$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_		-80 -100	nA	V _{DS} = -4.5V, V _{GS} = 0V V _{DS} = -20V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}			±10.0	μΑ	$V_{GS} = \pm 8V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)	400				'	, 50	
Gate Threshold Voltage	V _{GS(TH)}	-0.5	· -	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	
			0.7	1.0		$V_{GS} = -4.5V, I_{D} = -100mA$	
		1	0.9	1.5		$V_{GS} = -2.5V, I_{D} = -80mA$	
Static Drain-Source On-Resistance	R _{DS(ON)}	/ –	1.2	2.0	Ω	$V_{GS} = -1.8V, I_D = -40mA$	
		_	1.5	3.0		V _{GS} = -1.5V, I _D = -30mA	
		_	5	_		$V_{GS} = -1.2V, I_D = -1mA$	
Forward Transfer Admittance	Y _{fs}	_	0.7	_	S	$V_{DS} = -3V, I_{D} = -100mA$	
Diode Forward Voltage	▶ V _{SD}	_	-0.75	-1.2	V	$V_{GS} = 0V, I_{S} = -330mA$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	46.1	1		101/1/	
Output Capacitance	Coss	_	7.2	1	pF	$V_{DS} = -10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	4.9	-		1 - 1.000112	
Total Gate Charge V _{GS} = -4.5V	Q_g	_	0.5	1			
Total Gate Charge V _{GS} = -8V	Q_{g}	_	0.8	1	nC	$V_{DS} = -10V, I_{D} = -250 \text{mA}$	
Gate-Source Charge	Q_{gs}	_	0.1		110	V _{DS} = -10V, I _D = -250IIIA	
Gate-Drain Charge	Q_{gd}	_	0.1				
Turn-On Delay Time	t _{D(ON)}	_	8.5	ı	_	0// // 0.5//	
Turn-On Rise Time			4.3	1		$V_{DD} = -3V$, $V_{GS} = -2.5V$,	
Turn-Off Delay Time	t _{D(OFF)}	_	20.2	-	ns	$R_L = 300\Omega, R_g = 25\Omega,$ $I_D = -100 \text{mA}$	
Turn-Off Fall Time	t _F	_	19.2	1		ID = -100IIIA	

Notes:

- Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.





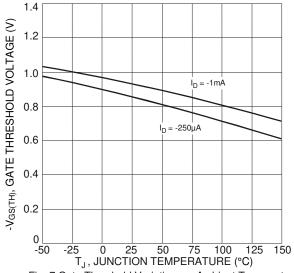
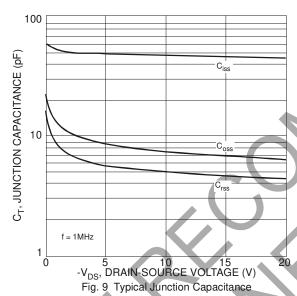
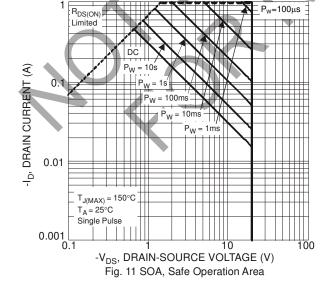
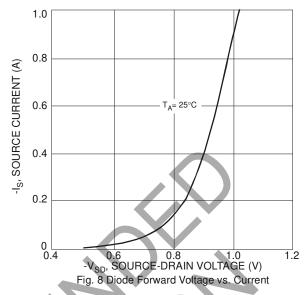
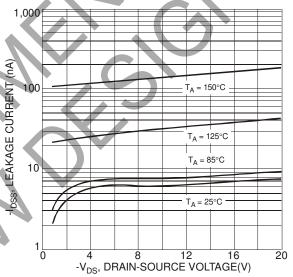


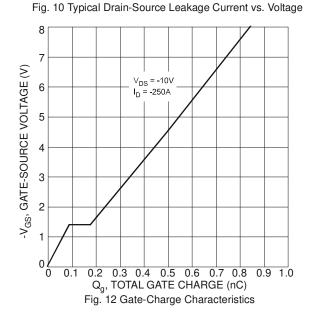
Fig. 7 Gate Threshold Variation vs. Ambient Temperature









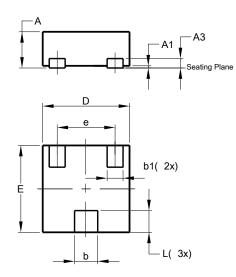




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1212-3

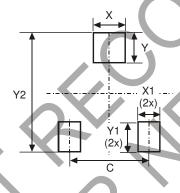


X1-DFN1212-3						
Dim	Min	Max	Тур			
Α	0.47	0.53	0.50			
A1	0	0.05	0.02			
A3	-	-	0.13			
b	0.27	0.37	0.32			
b1	0.17	0.27	0.22			
D	1.15	1.25	1.20			
E	1.15	1.25	1.20			
е	-	-	0.80			
L	0.25	0.35	0.30			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1212-3



Dimensions	Value (in mm)
С	0.80
Х	0.42
X1	0.32
Υ	0.50
Y1	0.50
V2	1.50



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